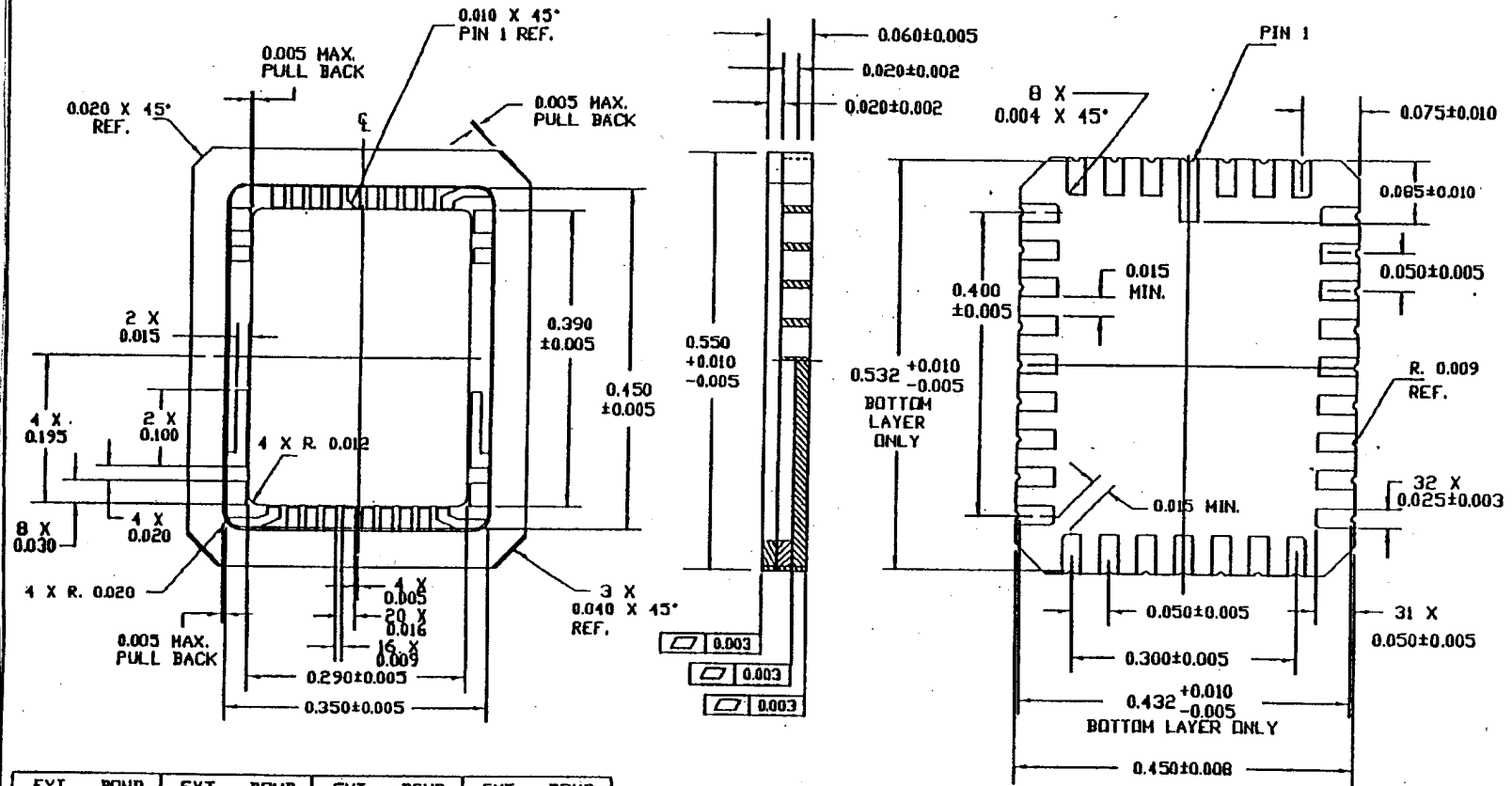


# SSM P/N LCC03209

**NOTES**

1. INTERPRET DRAWING PER BOM-STD-001.
2. DIMENSIONS ARE TYPICAL FOR ALL DIMENSIONS UNLESS OTHERWISE SPECIFIED.
3. FINISH: GOLD PLATE ON; DIODES MIN OVER; 50% BEAMS MIN. HEDGE.
4. BE ATTACH CAVITY AND SEAL RING WILL BE ELECTRICALLY ISOLATED.
5. LEAD RESISTANCE: 400 OHM MAX.
6. NO METAL IN DPA CAVITY.

DATE	REV	BY	DESCRIPTION	DATE	APPROVED
	011		NEW RELEASE	11/04/93	
	034		CORRECT NOTE 07 (TYPING ERROR)	03/08/94	
	099		CHG. NOTE 05	03/14/94	



EXT PIN	BOND PAD	EXT PIN	BOND PAD	EXT PIN	BOND PAD	EXT PIN	BOND PAD
1	1	9	9	17	15	25	21
2	2	10	10	18	N/C	26	22
3	3	11	N/C	19	16	27	23
4	4	12	11	20	17	28	24
5	5	13	12	21	18	29	25
6	6	14	13	22	19	30	26
7	7	15	N/C	23	N/C	31	27
8	8	16	14	24	20	32	28

DATE	REV	BY	DESCRIPTION	DATE	APPROVED
	011		NEW RELEASE	11/04/93	
	034		CORRECT NOTE 07 (TYPING ERROR)	03/08/94	
	099		CHG. NOTE 05	03/14/94	

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED		DATE: 11/04/93 BY: [Signature] TITLE: 32 LD LCC - 290 X 390
MATERIAL: [Blank] FINISH: SEE NOTE 3	PART NO: [Blank] REV: [Blank]	SCALE: 10:1 SHEET 1 OF 1

